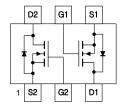


# 2N7002DW N-Channel Enhancement Mode Field Effect Transistor

## **Features**

- Dual N-Channel MOSFET
- · Low On-Resistance
- · Low Gate Threshold Voltage
- · Low Input Capacitance
- · Fast Switching Speed
- · Low Input/Output Leakage
- · Ultra-Small Surface Mount Package
- · Lead Free/RoHS Compliant





## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
2N7002DW	2N	SC70 6L	Tape and Reel

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter		Value	Unit	
V <sub>DSS</sub>	Drain-Source Voltage		60	V	
$V_{DGR}$	Drain-Gate Voltage (R <sub>GS</sub> ≤ 1.0 MΩ)		60	V	
V <sub>GSS</sub>	Gate-Source Voltage	Continuous	±20	V	
		Pulsed	±40	V	
I <sub>D</sub> Dra	Drain Current	Continuous	115	mA	
		Continuous at 100°C	73		
		Pulsed	800		
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-	-55 to +150	°C	

## **Thermal Characteristics**

Values are at T<sub>A</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit
P <sub>D</sub>	Total Device Dissipation	200	mW
	Derate Above T <sub>A</sub> = 25°C	1.6	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	625	°C/W

## Note:

1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. Minimum land pad size.

# **Electrical Characteristics**

Values are at  $T_A$  = 25°C unless otherwise noted.

Parameter	Conditions	Min.	Тур.	Max.	Unit	
Off Characteristics <sup>(2)</sup>						
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \mu\text{A}$	60	78		V	
Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		0.001	1.0	μА	
	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V},$ $T_{J} = 125^{\circ}\text{C}$		7	500		
Gate-Body Leakage	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V		0.2	±10	nA	
On Characteristics <sup>(2)</sup>						
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.00	1.76	2.00	V	
Static Drain-Source On-Resistance	V <sub>GS</sub> = 5 V, I <sub>D</sub> = 0.05 A		1.6	7.5	Ω	
	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A			2.0		
	$V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A},$ $T_J = 125^{\circ}\text{C}$		2.53	13.5		
On-State Drain Current	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 7.5 V	0.50	1.43		Α	
Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.2 A	80.0	356.5		mS	
Dynamic Characteristics						
Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		37.8	50	pF	
Output Capacitance			12.4	25	pF	
Reverse Transfer Capacitance	1.0 11.12		6.5	7	pF	
C <sub>rss</sub> Reverse Transfer Capacitance 6.5 7 pF  Switching Characteristics						
Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_{D} = 0.2 \text{ A}, \\ V_{GEN} = 10 \text{ V}, R_{L} = 150 \Omega, \\ R_{GEN} = 25 \Omega$		5.85	20	ns	
Turn-Off Delay Time			12.5	20	ns	
	Pristics (2) Drain-Source Breakdown Voltage  Zero Gate Voltage Drain Current  Gate-Body Leakage Pristics (2) Gate Threshold Voltage  Static Drain-Source On-Resistance  On-State Drain Current Forward Transconductance Paracteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance  Characteristics Turn-On Delay Time	eristics (2)Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 10 \text{ μA}$ Zero Gate Voltage Drain Current $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, V_{DS} = 60 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{DS} = 250 \text{ V}, V_{DS} = 0 \text{ V}$ eristics (2)Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \text{ μA}$ $V_{DS} = 5 \text{ V}, I_D = 0.05 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A}$ $V_{DS} = 10 \text{ V}, V_{DS} = 7.5 \text{ V}$ Forward Transconductance $V_{DS} = 10 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V_{DS} = 0.5 \text{ A}$ $V_{CS} = 10 \text{ V}, V_{DS} = 0.5 \text{ A}$ $V_{CS} = 10 \text{ V}, V_{DS} = 10 \text{ V}, V_{DS} = 7.5 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$ Forward Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ Provided Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ Provided Transconductance $V_{CS} = 25 \text{ V}, V_{CS} = 0 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ Provided Transconductance $V_{CS} = 25 \text{ V}, V_{CS} = 0 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ Provided Transconductance $V_{CS} = 25 \text{ V}, V_{CS} = 0 \text{ V}$ $V_{CS} = 10 \text{ V}, V_{CS} = 0 \text{ V}$ Provided Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 10 \text{ V}$ $V_{CS} = 10 \text{ V}$ Provided Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 10 \text{ V}$ Provided Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 10 \text{ V}$ Provided Transconductance $V_{CS} = 10 \text{ V}, V_{CS} = 10 \text{ V}$ Provided Transconductance <t< td=""><td>Pristics (2)         Drain-Source Breakdown Voltage         <math>V_{GS} = 0 \text{ V}, I_D = 10 \text{ μA}</math>         60         78           Zero Gate Voltage Drain Current         <math>V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}</math>         0.001           Zero Gate Voltage Drain Current         <math>V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}</math>         7           Gate-Body Leakage         <math>V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}</math>         0.2           Pristics (2)         Gate Threshold Voltage         <math>V_{DS} = V_{GS}, I_D = 250 \text{ μA}</math>         1.00         1.76           Static Drain-Source On-Resistance         <math>V_{GS} = 5 \text{ V}, I_D = 0.05 \text{ A}</math>         1.6         1.6           V<sub>GS</sub> = 10 V, I<sub>D</sub> = 0.5 A, T<sub>J</sub> = 125°C         2.53         2.53           On-State Drain Current         <math>V_{GS} = 10 \text{ V}, V_{DS} = 7.5 \text{ V}</math>         0.50         1.43           Forward Transconductance         <math>V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ A}</math>         80.0         356.5           Paracteristics           Input Capacitance         <math>V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, I_D = 0.2 \text{ A}</math>         12.4           Reverse Transfer Capacitance         <math>V_{DD} = 30 \text{ V}, I_D = 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L =</math></td><td>Peristics (2)         Drain-Source Breakdown Voltage         <math>V_{GS} = 0 \text{ V}, I_D = 10 \text{ μA}</math>         60         78           Zero Gate Voltage Drain Current         <math>V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}</math>         0.001         1.0           V<sub>DS</sub> = 60 V, V<sub>GS</sub> = 0 V, V<sub>DS</sub> = 0 V         7         500           Gate-Body Leakage         <math>V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}</math>         7         500           Gate Threshold Voltage         <math>V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}</math>         1.00         1.76         2.00           Static Drain-Source On-Resistance           V<sub>GS</sub> = 5 V, I<sub>D</sub> = 0.05 A         1.6         7.5           V<sub>GS</sub> = 10 V, I<sub>D</sub> = 0.5 A         2.0         2.53         13.5           On-State Drain Current         V<sub>GS</sub> = 10 V, I<sub>D</sub> = 0.5 A, T<sub>J</sub> = 125°C         2.53         13.5           On-State Transconductance         V<sub>DS</sub> = 10 V, I<sub>D</sub> = 0.2 A         80.0         356.5           Paracteristics           Input Capacitance         V<sub>DS</sub> = 25 V, V<sub>GS</sub> = 0 V, f = 1.0 MHz         12.4         25           Characteristics         7         5.85         20           Turn-On Delay Time         V<sub>DD</sub> = 30 V, I<sub>D</sub> = 0.2 A, V<sub>GEN</sub> = 10 V, R<sub>L</sub> = 150 Ω,         12.4         5.85         20</td></t<>	Pristics (2)         Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 10 \text{ μA}$ 60         78           Zero Gate Voltage Drain Current $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ 0.001           Zero Gate Voltage Drain Current $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ 7           Gate-Body Leakage $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ 0.2           Pristics (2)         Gate Threshold Voltage $V_{DS} = V_{GS}, I_D = 250 \text{ μA}$ 1.00         1.76           Static Drain-Source On-Resistance $V_{GS} = 5 \text{ V}, I_D = 0.05 \text{ A}$ 1.6         1.6           V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A, T <sub>J</sub> = 125°C         2.53         2.53           On-State Drain Current $V_{GS} = 10 \text{ V}, V_{DS} = 7.5 \text{ V}$ 0.50         1.43           Forward Transconductance $V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ A}$ 80.0         356.5           Paracteristics           Input Capacitance $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, I_D = 0.2 \text{ A}$ 12.4           Reverse Transfer Capacitance $V_{DD} = 30 \text{ V}, I_D = 0.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L = 150 \Omega, V_{GEN} = 10 \text{ V}, R_L =$	Peristics (2)         Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 10 \text{ μA}$ 60         78           Zero Gate Voltage Drain Current $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ 0.001         1.0           V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0 V         7         500           Gate-Body Leakage $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ 7         500           Gate Threshold Voltage $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ 1.00         1.76         2.00           Static Drain-Source On-Resistance           V <sub>GS</sub> = 5 V, I <sub>D</sub> = 0.05 A         1.6         7.5           V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A         2.0         2.53         13.5           On-State Drain Current         V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A, T <sub>J</sub> = 125°C         2.53         13.5           On-State Transconductance         V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.2 A         80.0         356.5           Paracteristics           Input Capacitance         V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz         12.4         25           Characteristics         7         5.85         20           Turn-On Delay Time         V <sub>DD</sub> = 30 V, I <sub>D</sub> = 0.2 A, V <sub>GEN</sub> = 10 V, R <sub>L</sub> = 150 Ω,         12.4         5.85         20	

#### Note:

2. Short duration test pulse used to minimize self-heating effect.

# **Typical Performance Characteristics**

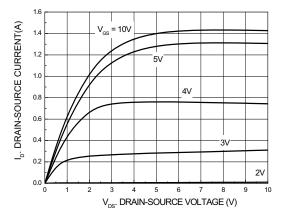


Figure 1. On-Region Characteristics

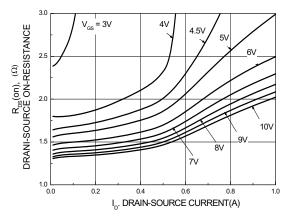


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

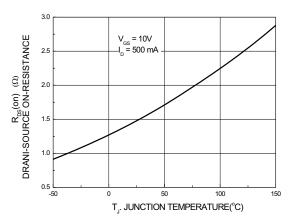


Figure 3. On-Resistance Variation with Temperature

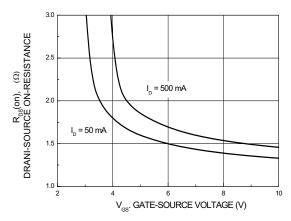


Figure 4. On-Resistance Variation with Gate-Source Voltage

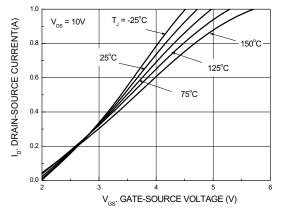


Figure 5. Transfer Characteristics

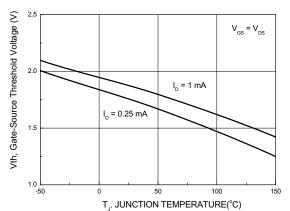


Figure 6. Gate Threshold Variation with Temperature

# **Typical Performance Characteristics** (Continued)

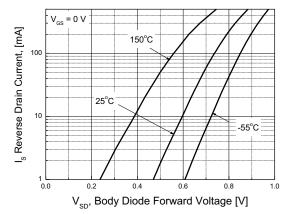


Figure 7. Reverse Drain Current Variation with Diode Forward Voltage and Temperature

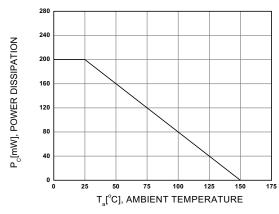


Figure 8. Power Derating

# **Physical Dimensions** SYMM 2.00±0.20 A 0.65 - 0.50 MIN В **PIN ONE** 1.25±0.10 0.30 0.15 (0.25) -0.40 MIN → 0.10M A B 0.65 LAND PATTERN RECOMMENDATION 1.30 1.00 0.80 SEE DETAIL A 1.10 0.80 0.10 0.00 0.10 C C 2.10±0.30 **SEATING** PLANE NOTES: UNLESS OTHERWISE SPECIFIED **GAGE** A) THIS PACKAGE CONFORMS TO EIAJ **PLANE** SC-88, 1996. (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS.

A) THIS PACKAGE CONFORMS TO EIAJ SC-88, 1996.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
D) DRAWING FILENAME: MKT-MAA06AREV6

Figure 9. 6-LEAD, SC70, EIAJ SC-88, 1.25MM WIDE

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